

Publikationen

- (2018): Protective nanometer films for reliable Cu-Cu connections. Invited Talk. In: IEEE International Reliability Physics Symposium (IRPS), San Francisco, CA, USA.
- (2018): Nanoscale thermal properties of next generation transparent/flexible thermoelectric copper iodide films. Posterpräsentation. In: 5. Tag der Forschung, Deggendorf.
- (2017): Nanoscale thermal properties of next generation transparent/flexible thermoelectric copper iodide films. Posterpräsentation. In: 5th Nano Today Conference, Hawaii, USA.
- (2017): Protective nanometer films for reliable Cu-Cu connections. Best Paper Award. In: Proceedings of the 28th European Symposium on Reliability of Electron Devices, Failure Physics and Analysis (ESREF) [25-28 September, 2017; Bordeaux, Frankreich].
- (2017): Transparent flexible thermoelectric material based on non-toxic earth-abundant p-type copper iodide thin film. In: nature COMMUNICATIONS, no. July. DOI: 10.1038/ncomms1607.
- (2017): Protective nanometer films for reliable Cu-Cu connections. In: Microelectronics Reliability, vol. 76-77, no. September, pp. 383-389. DOI: 10.1016/j.microrel.2017.07.001.
- (2015): Differential 3 ω method for measuring thermal conductivity of AlN and Si₃N₄ thin films. In: Thin Solid Films, vol. 591 Part B, pp. 267-270. DOI: 10.1016/j.tsf.2015.03.031.
- (2014): The differential 3 ω method for measuring the thermal conductivity of AlN and Si₃N₄ thin films. In: 16th International Conference on Thin Films (ICTF16), Dubrovnik, Kroatien.
- (2013): Determining the thermal conductivity of thin layers with the macroscopic 3 ω method. In: Applied Research Conference (ARC), Deggendorf.